

GRINDING APPARATUS

ABSTRACT OF THE DISCLOSURE

A grinding apparatus includes a holding table that holds a wafer, a grinding unit that grinds an exposed surface of the wafer held by the holding table, a detecting unit that detects a physical quantity used for determination of the state of exposure of a separation surface of the wafer, and a control unit having an exposure determining unit that determines the state of exposure of the separation surface on the basis of the physical quantity detected by the detecting unit.

[Fig. 1]